# Shan-Yuan Teng

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## research: enabling haptic experiences anywhere, anytime

My research aims at advancing a new generation of **haptic devices** (e.g., those that can create the sense of touch, forces, etc.) that exhibit properties that we became used to expecting from our mobile phones & wearables, **such as extreme mobility, availability anytime, etc**. To advance haptics into this new territory and grant it these novel properties, I engineer custom-made interactive devices that, for instance: allow to feel touch in mixed reality without encumbering our fingerpads, or even haptic devices with virtually infinite battery life. I have published this work as papers at top Human-Computer Interaction (HCI) conferences including **ACM CHI & UIST**, with **Best Paper Awards** and **Honorable Mention Awards**.

#### education

- 2023 PhD candidate (Computer Science) at University of Chicago, USA committee members: Pedro Lopes, Ken Nakagaki, Sean Follmer
- 2019 PhD student (Computer Science) at University of Chicago, USA Advisor: Pedro Lopes
- 2018 **MS (Degree Computer Science) at National Taiwan University, Taiwan**Thesis: Shape-changing Haptic Interfaces for Virtual Reality
  Advisor: Bing-Yu 'Robin' Chen
- 2016 BS (Degree Electrical Engineering) at National Taiwan University, Taiwan

## fellowship

Eckhardt Graduate Scholarship (2019-2024), University of Chicago William Rainey Harper Dissertation Fellowship (2023-2024), University of Chicago

#### academic awards

**Best Paper Awards:** UIST 2021, UIST 2020 **Best Demo Awards:** UIST 2021 (x2)

Honorable Mention Awards: UIST 2022, CHI 2021, CHI 2020, UIST 2019

# publications

- [16] Haptic Permeability: adding holes to tactile devices improves dexterity. **Shan-Yuan Teng**, Aryan Gupta, Pedro Lopes. *In Proc. CHI 2024*.
- [15] ThermalRouter: enabling users to design thermally-sound devices. Alex Mazursky, Borui Li, Shan-Yuan Teng, Daria Shifrina, Joyce E. Passananti, Svitlana Midianko, Pedro Lopes. In Proc. UIST 2023.
- [14] Prolonging VR haptic experiences by harvesting kinetic energy from the user.

  Shan-Yuan Teng, K. D. Wu, Jacqueline Chen, Pedro Lopes. *In Proc. UIST 2022*.

  UIST Honorable Mention for Best Paper
- [13] Touch&Fold: a foldable haptic actuator for rendering touch in mixed reality.

  Shan-Yuan Teng, Pengyu Li, Romain Nith, Joshua Fonseca, Pedro Lopes. In Proc. CHI 2021.

  CHI Honorable Mention for Best Paper
- [12] Altering perceived softness of real rigid objects by restricting fingerpad deformation. Yujie Tao, **Shan-Yuan Teng**, Pedro Lopes. *In Proc. UIST 2021*.

  \*\*\*UIST Best Paper Award\*\*

  \*\*UIST Best Demo Award\*\*

- [11] DextrEMS: increasing dexterity in electrical muscle stimulation by combining it with brakes. Romain Nith, Shan-Yuan Teng, Pengyu Li, Yujie Tao, Pedro Lopes. In Proc. UIST 2021. TUIST Best Demo Award
- [10] MagnetIO: passive yet interactive soft haptic patches anywhere. Alex Mazursky, Shan-Yuan Teng, Romain Nith, Pedro Lopes. In Proc. CHI 2021.
- [9] Stereo-smell via electrical trigeminal stimulation. Jas Brooks, Shan-Yuan Teng, Jingxuan Wen, Romain Nith, Jun Nishida, Pedro Lopes. In Proc. CHI 2021.
- [8] Elevate: a walkable pin-array. Seungwoo Je, Hyunseung Lim, Kongpyung Moon, Shan-Yuan Teng, Jas Brooks, Pedro Lopes, and Andrea Bianchi. In Proc. CHI 2021.
- [7] A stretchable and strain-unperturbed pressure sensor for motion-interference-free tactile monitoring on skins. Qi Su, Q. Zou, Yang Li, Yuzhen Chen, Shan-Yuan Teng, Jane Tunde Kelleher, Romain Nith, Ping Cheng, Nan Li, Wei Liu, Shilei Dai, Youdi Liu, Alex Mazursky, Jie Xu, Lihua Jin, Pedro Lopes, Sihong Wang. Science Advances, 2021.
- [6] HandMorph: a passive exoskeleton that miniaturizes grasp. Jun Nishida, Soichiro Matsuda, Hiroshi Matsui, Shan-Yuan Teng, Ziwei Liu, Kenji Suzuki, Pedro Lopes. In Proc. UIST 2020. **Y** UIST Best Paper Award
- [5] Wearable microphone jamming. Shan-Yuan Teng\*, Yuxin Chen\*, Huiving Li\*, Steven Nagels, Zhijing Li, Pedro Lopes, Ben Y. Zhao, Haitao Zheng. (\*equal contribution) In Proc. CHI 2020. **CHI Honorable Mention for Best Paper**
- [4] TilePoP: tile-type pop-up prop for virtual reality. Shan-Yuan Teng, Cheng-Lung Lin, Chi-huan Chiang, Tzu-Sheng Kuo, Liwei Chan, Da-Yuan Huang, Bing-Yu Chen. In Proc. UIST 2019. UIST Honorable Mention for Best Paper UIST Honorable Mention for Best Talk
- [3] Aarnio: passive kinesthetic force output for foreground interactions on an interactive chair. Shan-Yuan Teng, Da-Yuan Huang, Chi Wang, Teddy Seyed, Jun Gong, Xing-Dong Yang, Bing-Yu Chen. In Proc. CHI 2019.
- [2] PuPoP: pop-up prop on palm for virtual reality. Shan-Yuan Teng, Tzu-Sheng Kuo, Chi Wang, Chi-huan Chiang, Da-Yuan Huang, Liwei Chan, Bing-Yu Chen. In Proc. UIST 2018.
- [1] Outside-In: visualizing out-of-sight regions-of-interest in a 360 video using spatial picture-in-picture Yung-Ta Lin, Yi-Chi Liao, Shan-Yuan Teng, Yi-Ju Chung, Liwei Chan, Bing-Yu Chen. In Proc. UIST 2017.

#### demonstrations

- [5] Touch&Fold: a foldable haptic actuator for rendering touch in mixed reality. Shan-Yuan Teng.
  - Chicago South Side Science Festival 2023
- [4] Touch&Fold: a foldable haptic actuator for rendering touch in mixed reality. Shan-Yuan Teng, Pedro Lopes. IEEE World Haptics 2023
- [3] Demonstrating Touch&Fold: a foldable haptic actuator for rendering touch in mixed reality. Shan-Yuan Teng, Pengyu Li, Romain Nith, Joshua Fonseca, Pedro Lopes. SIGGRAPH 2021 Emerging Technologies

- [2] Demonstrating MagnetIO: passive yet interactive soft haptic patches anywhere. Alex Mazursky, **Shan-Yuan Teng**, Romain Nith, Pedro Lopes. SIGGRAPH 2021 Emerging Technologies
- [1] Stylus Assistant: designing dynamic constraints for facilitating stylus inputs on portable displays. Long-Fei Lin, **Shan-Yuan Teng**, Rong-Hao Liang, Bing-Yu Chen. SIGGRAPH ASIA 2016 Emerging Technologies

#### workshop

- [3] Experience Haptics Seamlessly Across Virtual and Real Worlds.
  Shan-Yuan Teng, Pedro Lopes. IEEE VR 2024: 1st Workshop on Seamless Reality:
  AR Technologies for Seamless Perception and Cognition between Cyber and Physical Spaces
- [2] Enabling Haptic Experiences Anywhere, Anytime. **Shan-Yuan Teng**. SIGGRAPH 2022 Frontiers Workshop: Challenges to Unlock the Metaverse: Haptics, Gaze, Prototyping tools & more!
- [1] Building Miniature and Standalone Haptic Wearables for Integrating into the Real World. Romain Nith, **Shan-Yuan Teng**, Pedro Lopes. *CHI* 2022: Sustainable Haptic Design

## magazine article

[1] XR Needs "Mixed Feelings": engineering haptic devices that work in both virtual and physical realities.

Shan-Yuan Teng, Pedro Lopes. ACM XRDS 2022: Crossroads Magazine Article

#### student research projects

- [2] Way Out: a multi-layer panorama mobile game using around-body interactions. **Shan-Yuan Teng**, Mu-Hsuan Chen, Yung-Ta Lin. *CHI 2017 Student Game Competition*.
- [1] Playing air guitar using electrical muscle stimulation.

  Shan-Yuan Teng, Yung-Ta Lin, Yi-Chi Liao. UIST 2016 Student Innovation Contest.

  UIST SIC Best Implementation Award

#### invited talks

- [9] Stanford University (2023)

  HCI Lunch organized by Yujie Tao & Matthew Jörke
- [8] Eindhoven University of Technology (2023) Hosted by Rong-Hao Liang
- [7] ACM CHI Doctoral Consortium (2023) Led by Margaret Burnett, Kasper Hornbæk
- [6] National Taiwan University (2022) Hosted by Lung-Pan Cheng
- [5] University of Notre Dame (2022) Hosted by Toby Jia-Jun Li
- [4] Simon Fraser University (2022) Hosted by Xing-Dong Yang
- [3] SIGGRAPH Frontiers Workshop (2022) Co-present with Michael Nebeling, Mark Billinghurst, Pedro Lopes, Yudai Tanaka
- [2] University of California, Los Angeles (2022) Hosted by Yang Zhang
- [1] Taiwanese Association of Computer Human Interaction (2021) Hosted by Liwei Chan

# teaching assistant

- [5] "Make Your Own Wearables From Scratch"

  Workshop for Chicago Public Schools hosted by the University of Chicago, 2023.
- [4] Inventing, Engineering and Understanding Interactive Devices (CMSC 23220) Spring 2022 course at the University of Chicago.
- [3] Engineering Interactive Electronics onto Printed Circuit Boards (CMSC 23230/CMSC 33230) Spring 2021 course at the University of Chicago.
- [2] Emerging Interface Technologies (CMSC 33240/CMSC 23240) Winter 2020 course at the University of Chicago.
- [1] Introduction to Human-Computer Interaction (CMSC 20300) Fall 2019 course at the University of Chicago.

## professional service

Program Committee: ACM SUI 2023/2024, ACM Augmented Humans 2023/2024, ACM ISWC 2022

**Demo Chair:** ACM Augmented Humans 2021 **Paper Session Chair:** ACM CHI 2022/2023

Paper Reviewer: ACM CHI, UIST, TEI, DIS, IMX, SIGGRAPH (Technical Paper)

IEEE VR, IEEE Haptics, IEEE ISMAR, IEEE World Haptics

International Journal of Human-Computer Studies

Student Volunteer: ACM UIST 2022 PC Meeting, IEEE Haptics 2022, ACM UIST 2020